IN THE ABSTRACT:

A PACKAGED INTEGRATED CIRCUIT HAVING A HEAT SPREADER AND METHOD THEREFOR

Abstract of the Disclosure

An integrated circuit ~~(60)~~ is packaged, in one embodiment, by wire bonding to pads ~~(76, 78)~~ supported by tape ~~(83)~~. The tape ~~(83)~~ also supports traces ~~(80, 82)~~ that run from the wire bonded location ~~(76)~~ to a pad for solder balls ~~(90, 94)~~. A heat spreader ~~(69)~~ is thermally connected to the integrated circuit ~~(60)~~ and is located not just in the area under the die ~~(60)~~ but also extends to the edge of the package in the area outside the wire bonding location. This outer area ~~(68)~~ is thermally connected to the area ~~(66)~~ under the die ~~(60)~~ by thermal bars ~~(66)~~ that run between some of the wire bond locations ~~(76, 78)~~. During the manufacturing of the package the heat spreader ~~(69)~~ is connected to slotted rails by tie bars ~~(48, 50, 52, 54)~~. During singulation, the tie bars ~~(48, 50, 52, 54)~~ are easily broken or sawed because they are significantly reduced in thickness from the thickness of the heat spreader ~~(66)~~ as a whole.

~~FIG. 3 to accompany the abstract.~~